

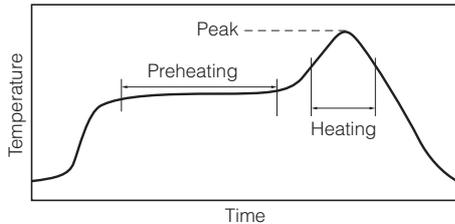
Recommended Soldering Conditions

Recommendations and precautions are described below.

● Rectangular Type

● Recommended soldering conditions for reflow

- Reflow soldering shall be performed a maximum of two times.
- Please contact us for additional information when used in conditions other than those specified.
- Please measure the temperature of the terminals and study every kind of solder and printed circuit board for solderability before actual use.



For soldering (Example : Sn/Pb)

	Temperature	Time
Preheating	140 °C to 160 °C	60 s to 120 s
Main heating	Above 200 °C	30 s to 40 s
Peak	235 ± 5 °C	max. 10 s

For lead-free soldering (Example : Sn/Ag/Cu)

	Temperature	Time
Preheating	150 °C to 180 °C	60 s to 120 s
Main heating	Above 230 °C	30 s to 40 s
Peak	max. 260 °C	max. 10 s

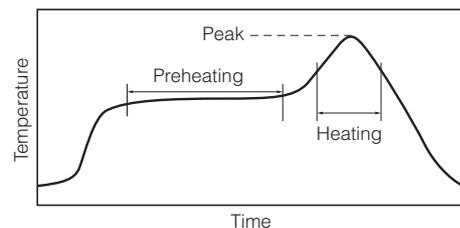
● Recommended soldering conditions for flow

	For soldering		For lead-free soldering	
	Temperature	Time	Temperature	Time
Preheating	140 °C to 180 °C	60 s to 120 s	150 °C to 180 °C	60 s to 120 s
Soldering	245 ± 5 °C	20 s to 30 s	max. 260 °C	max. 10 s

● Chip Resistor Array, Chip Resistor Networks and Chip Attenuator

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For soldering (Example : Sn/Pb)

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For lead-free soldering (Example : Sn/Ag/Cu)

	Temperature	Time
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Main heating	Above 230 °C	30 s to 40 s
Peak	max. 260 °C	max. 10 s

● Flow soldering

We do not recommend flow soldering, because a solder bridge may form. Please contact us regarding flow soldering of EXBA series.